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## **FACSIMILE TRANSMITTAL**

DATE:

January 18, 2005

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U.S. Patent & Trademark Office

**Examining Group 2800** 

FROM:

Steven M. Jensen

**FAX NO.:** 

1-703-872-9318

FAX NO.:

617-439-4170

Our Docket No.:

60173 (71987)

No. of Pages (incl. cover): 3

Re:

U.S. Serial Number 10/696,198

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Docket No. 60173 (71987)

# IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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APPLICANT:

C. Huang

JAN 1 8 2005

U.S. SERIAL NO:

10/696,198

EXAMINER: H. Trinh

FILED:

October 28, 2003

GROUP:

2814

FOR:

MULTI-CHIP PACKAGE DEVICE WITH HEAT SINK AND

FABRICATION METHOD THEREOF

### CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being transmitted by facsimile to Group 2800 of the U.S. Patent & Trademark Office by facsimile number 703-872-9318 on January 18, 2005.

Steven M. Jensen

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir/Madam:

### RESPONSE TO OFFICE ACTION

Applicant is in receipt of the Office Action dated December 15, 2004 of the above-identified application. This response is timely filed, because January 16, 2005 was a Sunday, and January 17, 2005 was a federal holiday.

In response to the Restriction Requirement, <u>Applicant provisionally elects Group I</u>, <u>claims 1-8</u>, <u>with traverse</u>. The present election is made solely to comply with the Office Action and should not be construed as a surrender of any subject matter of the application. Applicant reserves the right to file divisional application(s) on the non-elected claims.

C. J'uang U.S. Serial No. 10/696,198 Page 2 of 2

Applicant traverses the Restriction Requirement on the basis that, while the claims of Groups I and II are drawn to a multi-chip package device and a fabrication method, respectively, the Examiner has failed to demonstrate that the product as claimed can be made by "another and materially different process." According to MPEP §806.05(f), it is permissible to define a product in terms of a process by which it is made, in order to define the invention.

It was stated on page 2 of the Office Action: "In the instant case the product as claimed can be made with another materially different process such that the process includes the step of forming an external device" (emphasis added).

However, the proposed step of "forming an external device" falls outside the scope of the Applicant's claimed invention. For example, in the specification it is stated that solder balls 313 provide "electrical connection of the package device 3 with an external device (not shown)" (page 8, lines 19-20). In other words, the step of forming an external device is <u>not</u> shown in the drawings, and does <u>not</u> fall within the scope of the Applicant's claimed invention. Moreover, claim 1 (of Group I) does not require "forming an external device" but instead merely recites: "a chip carrier for electrically connecting the semiconductor package device to an external device" (emphasis added).

Withdrawal of the restriction requirement, and early consideration and allowance of the application are carnestly solicited.

Respectfully submitted,

Date: January 18, 2005

Peter F. Corless (Reg. No. 33,860) Steven M. Jensen (Reg. No. 42,693)

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